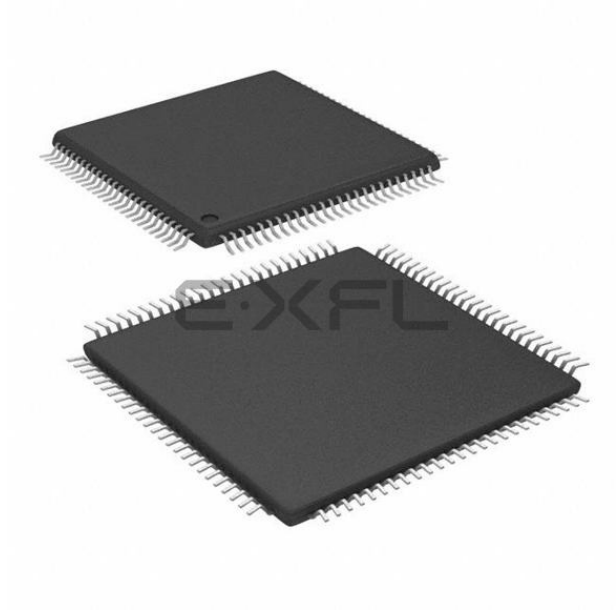
Microchip Technology - PIC24FJ128GB610T-I/PT Datasheet



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What is "Embedded - Microcontrollers"?

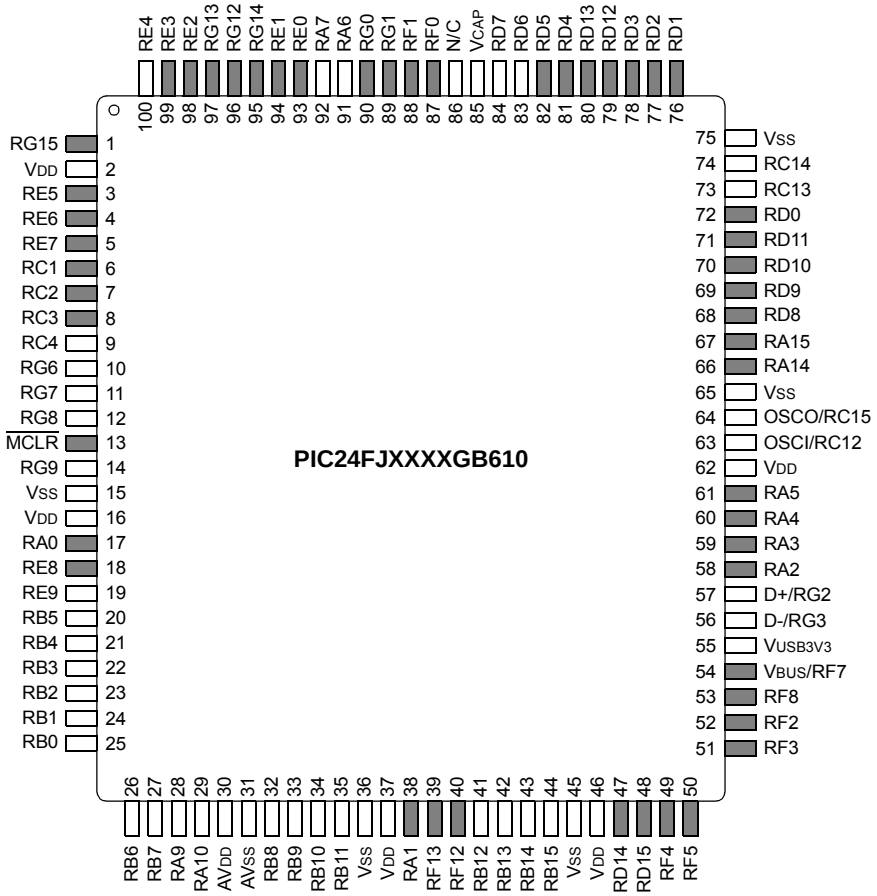
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj128gb610t-i-pt

Pin Diagrams(1) (Continued)

100-Pin TQFP

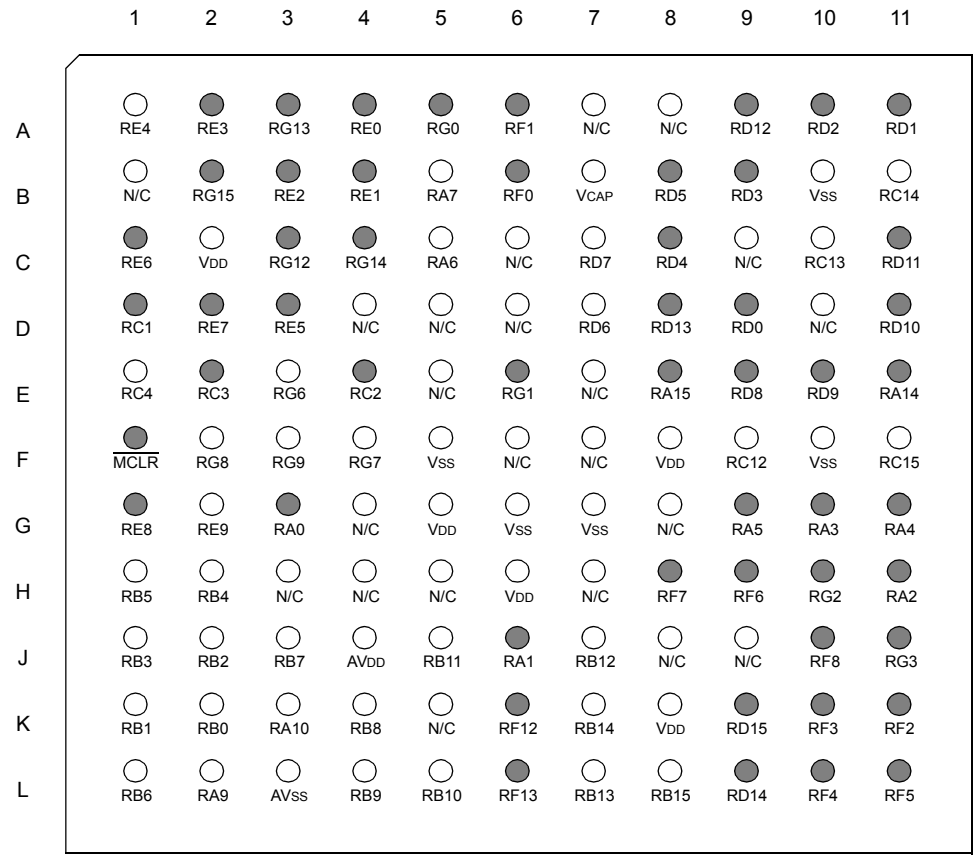


Legend: See Table 5 for a complete description of pin functions. Pinouts are subject to change.

Note 1: Gray shading indicates 5.5V tolerant input pins.

Pin Diagrams(1) (Continued)

PIC24FJXXXGA610 121-Pin BGA

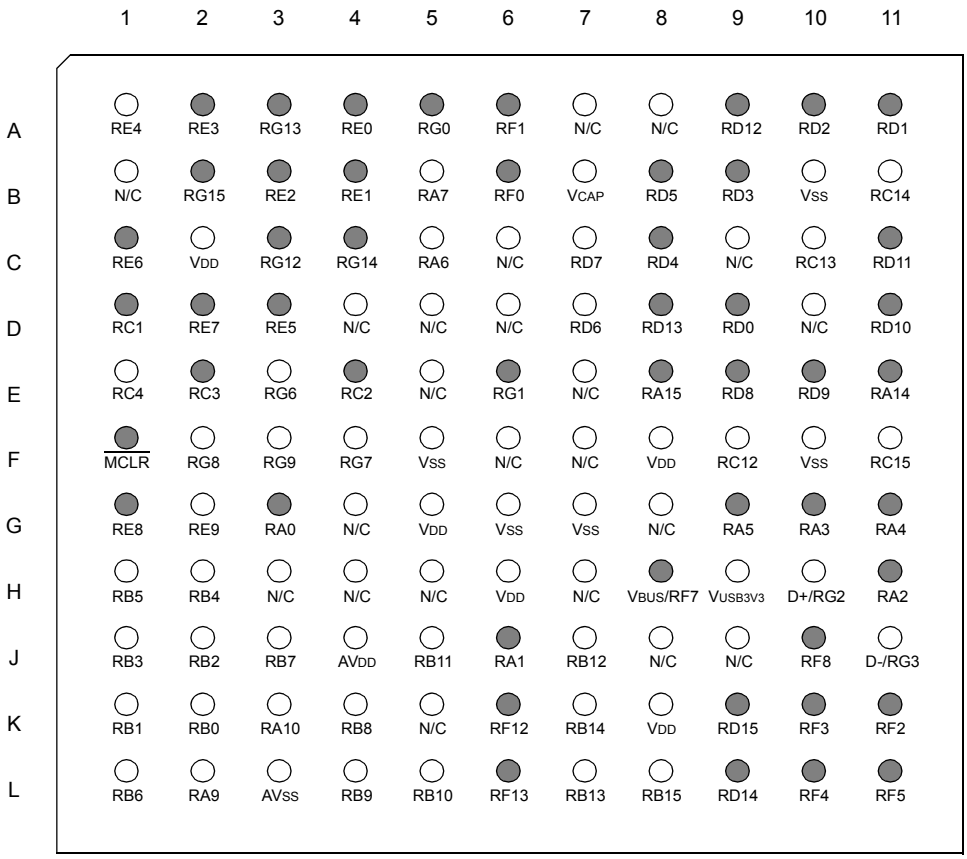


Legend: See Table 6 for a complete description of pin functions. Pinouts are subject to change.

Note 1: Gray shading indicates 5.5V tolerant input pins.

Pin Diagrams(1) (Continued)

PIC24FJXXXGB610 121-Pin BGA



Legend: See Table 7 for a complete description of pin functions. Pinouts are subject to change.
Note 1: Gray shading indicates 5.5V tolerant input pins.

TABLE 1-3: PIC24FJ1024GA610/GB610 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Pin Function	Pin Number/Grid Locator						I/O	Input Buffer	Description
	GA606 64-Pin QFN/TQFP/ QFP	GB606 64-Pin QFN/ TQFP/QFP	GA610 100-Pin TQFP/ QFP	GB610 100-Pin TQFP/ QFP	GA612 121-Pin BGA	GB612 121-Pin BGA			
RA0	—	—	17	17	G3	G3	I/O	DIG/ST	PORTA Digital I/Os
RA1	—	—	38	38	J6	J6	I/O	DIG/ST	
RA2	—	—	58	58	H11	H11	I/O	DIG/ST	
RA3	—	—	59	59	G10	G10	I/O	DIG/ST	
RA4	—	—	60	60	G11	G11	I/O	DIG/ST	
RA5	—	—	61	61	G9	G9	I/O	DIG/ST	
RA6	—	—	91	91	C5	C5	I/O	DIG/ST	
RA7	—	—	92	92	B5	B5	I/O	DIG/ST	
RA9	—	—	28	28	L2	L2	I/O	DIG/ST	
RA10	—	—	29	29	K3	K3	I/O	DIG/ST	
RA14	—	—	66	66	E11	E11	I/O	DIG/ST	
RA15	—	—	67	67	E8	E8	I/O	DIG/ST	
RB0	16	16	25	25	K2	K2	I/O	DIG/ST	PORTB Digital I/Os
RB1	15	15	24	24	K1	K1	I/O	DIG/ST	
RB2	14	14	23	23	J2	J2	I/O	DIG/ST	
RB3	13	13	22	22	J1	J1	I/O	DIG/ST	
RB4	12	12	21	21	H2	H2	I/O	DIG/ST	
RB5	11	11	20	20	H1	H1	I/O	DIG/ST	
RB6	17	17	26	26	L1	L1	I/O	DIG/ST	
RB7	18	18	27	27	J3	J3	I/O	DIG/ST	
RB8	21	21	32	32	K4	K4	I/O	DIG/ST	
RB9	22	22	33	33	L4	L4	I/O	DIG/ST	
RB10	23	23	34	34	L5	L5	I/O	DIG/ST	
RB11	24	24	35	35	J5	J5	I/O	DIG/ST	
RB12	27	27	41	41	J7	J7	I/O	DIG/ST	
RB13	28	28	42	42	L7	L7	I/O	DIG/ST	
RB14	29	29	43	43	K7	K7	I/O	DIG/ST	
RB15	30	30	44	44	L8	L8	I/O	DIG/ST	
RC1	—	—	6	6	D1	D1	I/O	DIG/ST	PORTC Digital I/Os
RC2	—	—	7	7	E4	E4	I/O	DIG/ST	
RC3	—	—	8	8	E2	E2	I/O	DIG/ST	
RC4	—	—	9	9	E1	E1	I/O	DIG/ST	
RC12	39	39	63	63	F9	F9	I/O	DIG/ST	
RC13	47	47	73	73	C10	C10	I/O	DIG/ST	
RC14	48	48	74	74	B11	B11	I/O	DIG/ST	
RC15	40	40	64	64	F11	F11	I/O	DIG/ST	

Legend: TTL = TTL input buffer
ANA = Analog level input/output
DIG = Digital input/output
ST = Schmitt Trigger input buffer
I^2C = I^2C/SMBus input buffer
XCVR = Dedicated Transceiver

2.4 Voltage Regulator Pin (VCAP)

Note: This section applies only to PIC24FJ devices with an on-chip voltage regulator.

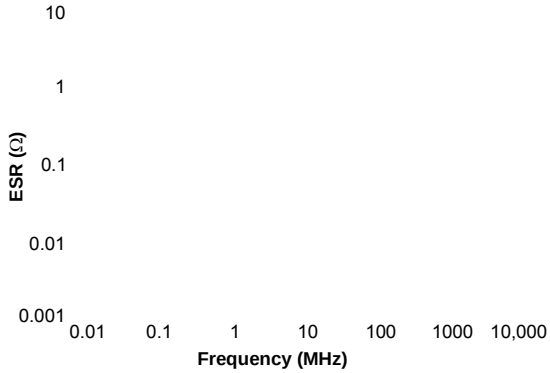
Refer to **Section 30.3 "On-Chip Voltage Regulator"** for details on connecting and using the on-chip regulator.

A low-ESR (< 5Ω) capacitor is required on the VCAP pin to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must use a capacitor of 10 µF connected to ground. The type can be ceramic or tantalum. Suitable examples of capacitors are shown in Table 2-1. Capacitors with equivalent specifications can be used.

Designers may use Figure 2-3 to evaluate the ESR equivalence of candidate devices.

The placement of this capacitor should be close to VCAP. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to **Section 33.0 "Electrical Characteristics"** for additional information.

FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP



Note: Typical data measurement at +25°C, 0V DC bias.

TABLE 2-1: SUITABLE CAPACITOR EQUIVALENTS (0805 CASE SIZE)

Make	Part #	Nominal Capacitance	Base Tolerance	Rated Voltage
TDK	C2012X5R1E106K085AC	10 µF	±10%	25V
TDK	C2012X5R1C106K085AC	10 µF	±10%	16V
Kemet	C0805C106M4PACTU	10 µF	±10%	16V
Murata	GRM21BR61E106KA3L	10 µF	±10%	25V
Murata	GRM21BR61C106KE15	10 µF	±10%	16V

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

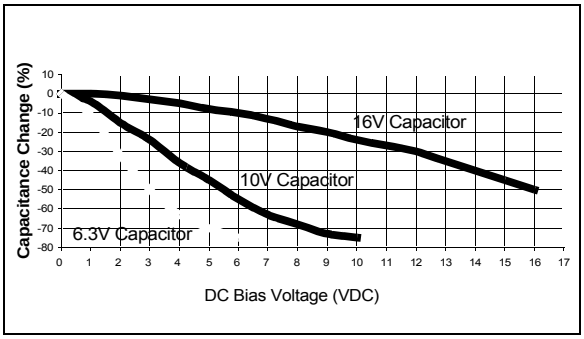
Typical low-cost, 10 μF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R) or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 μF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at a minimum of 16V for the 1.8V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

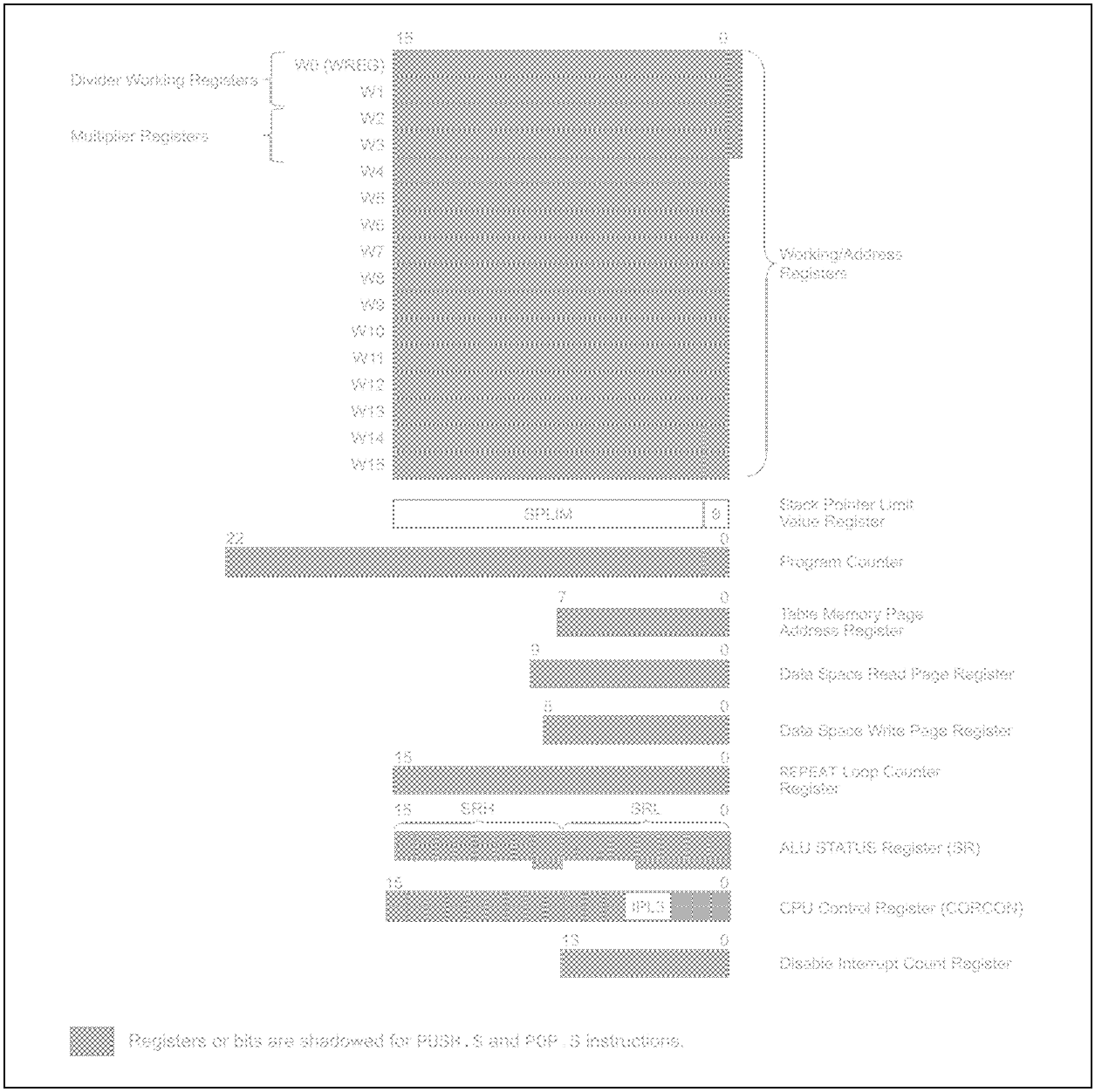
The PGECx and PGEDx pins are used for In-Circuit Serial Programming (ICSP) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

For device emulation, ensure that the "Communication Channel Select" pins (i.e., PGECx/PGEDx), programmed into the device, match the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 31.0 "Development Support"**.

FIGURE 3-2: PROGRAMMER'S MODEL



REGISTER 5-3: DMAINTn: DMA CHANNEL n INTERRUPT REGISTER

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DBUFWF(1)	CHSEL6	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
HIGHIF(1,2)	LOWIF(1,2)	DONEIF(1)	HALFIF(1)	OVRUNIF(1)	—	—	HALFEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **DBUFWF:** DMA Buffered Data Write Flag bit(1)
- 1 = The content of the DMA buffer has not been written to the location specified in DMADSTn or DMASRCn in Null Write mode
- 0 = The content of the DMA buffer has been written to the location specified in DMADSTn or DMASRCn in Null Write mode

bit 14-8 **CHSEL<6:0>:** DMA Channel Trigger Selection bits

See Table 5-1 for a complete list.

bit 7 **HIGHIF:** DMA High Address Limit Interrupt Flag bit(1,2)
- 1 = The DMA channel has attempted to access an address higher than DMAH or the upper limit of the data RAM space
- 0 = The DMA channel has not invoked the high address limit interrupt

bit 6 **LOWIF:** DMA Low Address Limit Interrupt Flag bit(1,2)
- 1 = The DMA channel has attempted to access the DMA SFR address lower than DMAL, but above the SFR range (07FFh)
- 0 = The DMA channel has not invoked the low address limit interrupt

bit 5 **DONEIF:** DMA Complete Operation Interrupt Flag bit(1)

If CHEN = 1:
- 1 = The previous DMA session has ended with completion
- 0 = The current DMA session has not yet completed

If CHEN = 0:
- 1 = The previous DMA session has ended with completion
- 0 = The previous DMA session has ended without completion

bit 4 **HALFIF:** DMA 50% Watermark Level Interrupt Flag bit(1)
- 1 = DMACNTn has reached the halfway point to 0000h
- 0 = DMACNTn has not reached the halfway point

bit 3 **OVRUNIF:** DMA Channel Overrun Flag bit(1)
- 1 = The DMA channel is triggered while it is still completing the operation based on the previous Trigger
- 0 = The overrun condition has not occurred

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **HALFEN:** Halfway Completion Watermark bit
- 1 = Interrupts are invoked when DMACNTn has reached its halfway point and at completion
- 0 = An interrupt is invoked only at the completion of the transfer

Note 1: Setting these flags in software does not generate an interrupt.

2: Testing for address limit violations (DMASRCn or DMADSTn is either greater than DMAH or less than DMAL) is NOT done before the actual access.

REGISTER 6-1: NVMCON: FLASH MEMORY CONTROL REGISTER (CONTINUED)

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits(1,2)

1110 = Chip erase user memory (does not erase Device ID, customer OTP or executive memory)
1000 = The next WR command will program FBOOT with the data held in the first 48 bits of the write latch and then will program the Dual Partition Signature (SIGN) bit in Flash. The device must be reset before the newly programmed mode can take effect.
0100 = Erase user memory and Configuration Words in the Inactive Partition (Dual Partition modes only)
0011 = Erase a page of program or executive memory
0010 = Row programming operation
0001 = Double-word programming operation

Note 1: These bits can only be reset on a Power-on Reset.

2: All other combinations of NVMOP<3:0> are unimplemented.

3: This bit may be cleared by software or by any Reset.

4: The WR bit should always be polled to indicate completion during any Flash memory program or erase operation while in Single Partition Mode.

REGISTER 8-1: SR: ALU STATUS REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1'= Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)
111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see Register 3-1.

2: The IPL<2:0> Status bits are concatenated with the IPL3 Status bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1. User interrupts are disabled when IPL3 = 1.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

11.4.5 CONSIDERATIONS FOR PERIPHERAL PIN SELECTION

The ability to control Peripheral Pin Selection introduces several considerations into application design that could be overlooked. This is particularly true for several common peripherals that are available only as remappable peripherals.

The main consideration is that the Peripheral Pin Selects are not available on default pins in the device's default (Reset) state. Since all RPINRx registers reset to '111111' and all RPORx registers reset to '000000', all Peripheral Pin Select inputs are tied to Vss, and all Peripheral Pin Select outputs are disconnected.

This situation requires the user to initialize the device with the proper peripheral configuration before any other application code is executed. Since the IOLOCK bit resets in the unlocked state, it is not necessary to execute the unlock sequence after the device has come out of Reset. For application safety, however, it is best to set IOLOCK and lock the configuration after writing to the control registers.

Because the unlock sequence is timing-critical, it must be executed as an assembly language routine in the same manner as changes to the oscillator configuration. If the bulk of the application is written in 'C', or another high-level language, the unlock sequence should be performed by writing in-line assembly.

Choosing the configuration requires the review of all Peripheral Pin Selects and their pin assignments, especially those that will not be used in the application. In all cases, unused pin-selectable peripherals should be disabled completely. Unused peripherals should have their inputs assigned to an unused RPn/RPIn pin function. I/O pins with unused RPn functions should be configured with the null peripheral output.

The assignment of a peripheral to a particular pin does not automatically perform any other configuration of the pin's I/O circuitry. In theory, this means adding a pin-selectable output to a pin may mean inadvertently driving an existing peripheral input when the output is driven. Users must be familiar with the behavior of other fixed peripherals that share a remappable pin and know when to enable or disable them. To be safe, fixed digital peripherals that share the same pin should be disabled when not in use.

Along these lines, configuring a remappable pin for a specific peripheral does not automatically turn that feature on. The peripheral must be specifically configured for operation and enabled as if it were tied to a fixed pin. Where this happens in the application code (immediately following a device Reset and peripheral configuration or inside the main application routine) depends on the peripheral and its use in the application.

A final consideration is that Peripheral Pin Select functions neither override analog inputs nor reconfigure pins with analog functions for digital I/O. If a pin is configured as an analog input on a device Reset, it must be explicitly reconfigured as a digital I/O when used with a Peripheral Pin Select.

Example 11-4 shows a configuration for bidirectional communication with flow control using UART1. The following input and output functions are used:

- Input Functions: U1RX, $\overline{\text{U1CTS}}$
- Output Functions: U1TX, $\overline{\text{U1RTS}}$

EXAMPLE 11-4: CONFIGURING UART1 INPUT AND OUTPUT FUNCTIONS

```
//  Unlock Registers
asm volatile    ("MOV   #OSCCON, w1   \n"
                 "MOV    #0x46, w2    \n"
                 "MOV    #0x57, w3    \n"
                 "MOV.b  w2, [w1]     \n"
                 "MOV.b  w3, [w1]     \n"
                 "BCLR   OSCCON, #6")  ;

//  or use XC16 built-in macro:
//  __builtin_write_OSCCONL(OSCCON & 0xbf);

//  Configure Input Functions (Table 11-3)
    // Assign U1RX To Pin RP0
    RPINR18bits.U1RXR = 0;

    // Assign U1CTS To Pin RP1
    RPINR18bits.U1CTSR = 1;

//  Configure Output Functions (Table 11-4)
    // Assign U1TX To Pin RP2
    RPOR1bits.RP2R = 3;

    // Assign U1RTS To Pin RP3
    RPOR1bits.RP3R = 4;

//  Lock Registers
asm volatile   ("MOV   #OSCCON, w1   \n"
                "MOV    #0x46, w2    \n"
                "MOV    #0x57, w3    \n"
                "MOV.b  w2, [w1]     \n"
                "MOV.b  w3, [w1]     \n"
                "BSET   OSCCON, #6")  ;

//  or use XC16 built-in macro:
//  __builtin_write_OSCCONL(OSCCON | 0x40);
```

REGISTER 11-18: RPINR6: PERIPHERAL PIN SELECT INPUT REGISTER 6

U-0	U-0	r-1	r-1	r-1	r-1	r-1	r-1
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	r-1	r-1	r-1	r-1	r-1	r-1
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **Reserved**: Maintain as ‘1’

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **Reserved**: Maintain as ‘1’

REGISTER 11-19: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **IC2R<5:0>:** Assign Input Capture 2 (IC2) to Corresponding RPn or RPIn Pin bits

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **IC1R<5:0>:** Assign Input Capture 1 (IC1) to Corresponding RPn or RPIn Pin bits

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 4 **OCFLT0:** PWM Fault 0 (OCFA pin) Condition Status bit(2,4)
- 1 = PWM Fault 0 has occurred
- 0 = No PWM Fault 0 has occurred

bit 3 **TRIGMODE:** Trigger Status Mode Select bit
- 1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
- 0 = TRIGSTAT is only cleared by software

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits(1)
- 111 = Center-Aligned PWM mode on OCx(2)
- 110 = Edge-Aligned PWM mode on OCx(2)
- 101 = Double Compare Continuous Pulse mode: Initialize the OCx pin low; toggle the OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initialize the OCx pin low; toggle the OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare Continuous Pulse mode: Compare events continuously toggle the OCx pin
- 010 = Single Compare Single-Shot mode: Initialize OCx pin high; compare event forces the OCx pin low
- 001 = Single Compare Single-Shot mode: Initialize OCx pin low; compare event forces the OCx pin high
- 000 = Output compare channel is disabled

Note 1: The OCx output must also be configured to an available RPn pin. For more information, see **Section 11.4 "Peripheral Pin Select (PPS)"**.

2: The Fault input enable and Fault status bits are valid when OCM<2:0> = 111 or 110.

3: The Comparator 1 output controls the OC1-OC3 channels, Comparator 2 output controls the OC4-OC6 channels, Comparator 3 output controls the OC7-OC9 channels.

4: The OCFA/OCFB Fault inputs must also be configured to an available RPn/RPIn pin. For more information, see **Section 11.4 "Peripheral Pin Select (PPS)"**.

16.5 Auxiliary Output

The MCCPx and SCCPx modules have an auxiliary (secondary) output that provides other peripherals access to internal module signals. The auxiliary output is intended to connect to other MCCPx or SCCPx modules, or other digital peripherals, to provide these types of functions:

- Time Base Synchronization
- Peripheral Trigger and Clock Inputs
- Signal Gating

The type of output signal is selected using the AUXOUT<1:0> control bits (CCPxCON2H<4:3>). The type of output signal is also dependent on the module operating mode.

On the PIC24FJ1024GA610/GB610 family of devices, only the CTMU discharge Trigger has access to the auxiliary output signal.

TABLE 16-4: AUXILIARY OUTPUT

AUXOUT<1:0>	CCSEL	MOD<3:0>	Comments	Signal Description
00	x	xxxx	Auxiliary Output Disabled	No Output
01	0	0000	Time Base Modes	Time Base Period Reset or Rollover
10				Special Event Trigger Output
11				No Output
01	0	0001 through 1111	Output Compare Modes	Time Base Period Reset or Rollover
10				Output Compare Event Signal
11				Output Compare Signal
01	1	xxxx	Input Capture Modes	Time Base Period Reset or Rollover
10				Reflects the Value of the ICDIS bit
11				Input Capture Event Signal

REGISTER 20-12: U1CNFG1: USB CONFIGURATION REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
UTEYE	UOEMON(1)	—	USBSIDL	—	—	PPB1	PPB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **UTEYE:** USB Eye Pattern Test Enable bit
- 1 = Eye pattern test is enabled
- 0 = Eye pattern test is disabled

bit 6 **UOEMON:** USB $\overline{OE}$ Monitor Enable bit(1)
- 1 = $\overline{OE}$ signal is active; it indicates intervals during which the D+/D- lines are driving
- 0 = $\overline{OE}$ signal is inactive

bit 5 **Unimplemented:** Read as '0'

bit 4 **USBSIDL:** USB OTG Stop in Idle Mode bit
- 1 = Discontinues module operation when the device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **PPB<1:0>:** Ping-Pong Buffers Configuration bits
- 11 = Even/Odd Ping-Pong Buffers are enabled for Endpoints 1 to 15
- 10 = Even/Odd Ping-Pong Buffers are enabled for all endpoints
- 01 = Even/Odd Ping-Pong Buffers are enabled for RX Endpoint 0
- 00 = Even/Odd Ping-Pong Buffers are disabled

Note 1: This bit is only active when the UTRDIS bit (U1CNFG2<0>) is set.

22.0 REAL-TIME CLOCK AND CALENDAR WITH TIMESTAMP

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Real-Time Clock and Calendar, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"RTCC with Timestamp"** (DS70005193), which is available from the Microchip web site (www.microchip.com). The information in this data sheet supersedes the information in the FRM.

The RTCC provides the user with a Real-Time Clock and Calendar (RTCC) function that can be calibrated.

Key features of the RTCC module are:

- Selectable Clock Source
- Provides Hours, Minutes and Seconds Using 24-Hour Format
- Visibility of One Half Second Period
- Provides Calendar – Weekday, Date, Month and Year
- Alarm-Configurable for Half a Second, 1 Second, 10 Seconds, 1 Minute, 10 Minutes, 1 Hour, 1 Day, 1 Week, 1 Month or 1 Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat Chime
- Year 2000 to 2099 Leap Year Correction
- BCD Format for Smaller Software Overhead
- Optimized for Long-Term Battery Operation
- User Calibration of the 32.768 kHz Clock Crystal/ 32K INTRC Frequency with Periodic Auto-Adjust
- Fractional Second Synchronization
- Calibration to within ±2.64 Seconds Error per Month
- Calibrates up to 260 ppm of Crystal Error
- Ability to Periodically Wake-up External Devices without CPU Intervention (external power control)
- Power Control Output for External Circuit Control
- Calibration takes Effect Every 15 Seconds
- Timestamp Capture Register for Time and Date
- Programmable Prescaler and Clock Divider Circuit Allows Operation with Any Clock Source up to 32 MHz, Including 32.768 kHz Crystal, 50/60 Hz Powerline Clock, External Real-Time Clock (RTC) or 31.25 kHz LPRC Clock

22.1 RTCC Source Clock

The RTCC clock divider block converts the incoming oscillator source into accurate 1/2 and 1 second clocks for the RTCC. The clock divider is optimized to work with three different oscillator sources:

- 32.768 kHz Crystal Oscillator
- 31 kHz Low-Power RC Oscillator (LPRC)
- External 50 Hz or 60 Hz Powerline Frequency

An asynchronous prescaler, PS<1:0> (RTCCON2L<5:4>), is provided that allows the RTCC to work with higher speed clock sources, such as the system clock. Divide ratios of 1:16, 1:64 or 1:256 may be selected, allowing sources up to 32 MHz to clock the RTCC.

22.1.1 COARSE FREQUENCY DIVISION

The clock divider block has a 16-bit counter used to divide the input clock frequency. The divide ratio is set by the DIV<15:0> register bits (RTCCON2H<15:0>). The DIV<15:0> bits should be programmed with a value to produce a nominal 1/2 second clock divider count period.

22.1.2 FINE FREQUENCY DIVISION

The fine frequency division is set using the FDIV<4:0> (RTCCON2L<15:11>) bits. Increasing the FDIVx value will lengthen the overall clock divider period.

If FDIV<4:0> = `00000`, the fine frequency division circuit is effectively disabled. Otherwise, it will optionally remove a clock pulse from the input of the clock divider every 1/2 second. This functionality will allow the user to remove up to 31 pulses over a fixed period of 16 seconds, depending on the value of FDIVx.

The value for DIV<15:0> is calculated as shown in Equation 22-1. The fractional remainder of the DIV<15:0> calculation result can be used to calculate the value for FDIV<4:0>.

EQUATION 22-1: RTCC CLOCK DIVIDER OUTPUT FREQUENCY

$$F_{OUT} = \frac{F_{IN}}{2 \bullet (PS\text{<1:0>}\ Prescaler) \bullet (DIV\text{<15:0>} + 1) + \left(\frac{FDIV\text{<4:0>}}{32}\right)}$$

The DIV<15:0> value is the integer part of this calculation:

$$DIV\text{<15:0>} = \frac{F_{IN}}{2 \bullet (PS\text{<1:0>}\ Prescaler)} - 1$$

The FDIV<4:0> value is the fractional part of the DIV<15:0> calculation multiplied by 32.

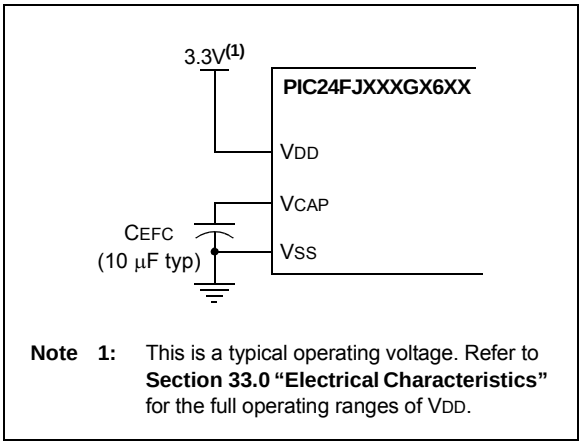
30.3 On-Chip Voltage Regulator

All PIC24FJ1024GA610/GB610 family devices power their core digital logic at a nominal 1.8V. This may create an issue for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the PIC24FJ1024GA610/GB610 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

This regulator is always enabled. It provides a constant voltage (1.8V nominal) to the digital core logic, from a VDD of about 2.1V, all the way up to the device's VDDMAX. It does not have the capability to boost VDD levels. In order to prevent "brown-out" conditions when the voltage drops too low for the regulator, the Brown-out Reset occurs. Then, the regulator output follows VDD with a typical voltage drop of 300 mV.

A low-ESR capacitor (such as ceramic) must be connected to the VCAP pin (Figure 30-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor (CEFC) is provided in **Section 33.1 "DC Characteristics"**.

FIGURE 30-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: This is a typical operating voltage. Refer to **Section 33.0 "Electrical Characteristics"** for the full operating ranges of VDD.

30.3.1 ON-CHIP REGULATOR AND POR

The voltage regulator takes approximately 10 μs for it to generate output. During this time, designated as TVREG, code execution is disabled. TVREG is applied every time the device resumes operation after any power-down, including Sleep mode. TVREG is determined by the status of the VREGS bit (RCON<8>) and the WDTWIN<1:0> Configuration bits (FWDT<9:8>). Refer to **Section 33.0 "Electrical Characteristics"** for more information on TVREG.

Note:	For more information, see **Section 33.0 "Electrical Characteristics"**. The information in this data sheet supersedes the information in the FRM.

30.3.2 VOLTAGE REGULATOR STANDBY MODE

The on-chip regulator always consumes a small incremental amount of current over IDD/IPD, including when the device is in Sleep mode, even though the core digital logic does not require power. To provide additional savings in applications where power resources are critical, the regulator can be made to enter Standby mode on its own whenever the device goes into Sleep mode. This feature is controlled by the VREGS bit (RCON<8>). Clearing the VREGS bit enables the Standby mode. When waking up from Standby mode, the regulator needs to wait for TVREG to expire before wake-up.

30.3.3 LOW-VOLTAGE/RETENTION REGULATOR

When in Sleep mode, PIC24FJ1024GA610/GB610 family devices may use a separate low-power, low-voltage/retention regulator to power critical circuits. This regulator, which operates at 1.2V nominal, maintains power to data RAM and the RTCC while all other core digital logic is powered down. The low-voltage/retention regulator is described in more detail in **Section 10.2.4 "Low-Voltage Retention Regulator"**.

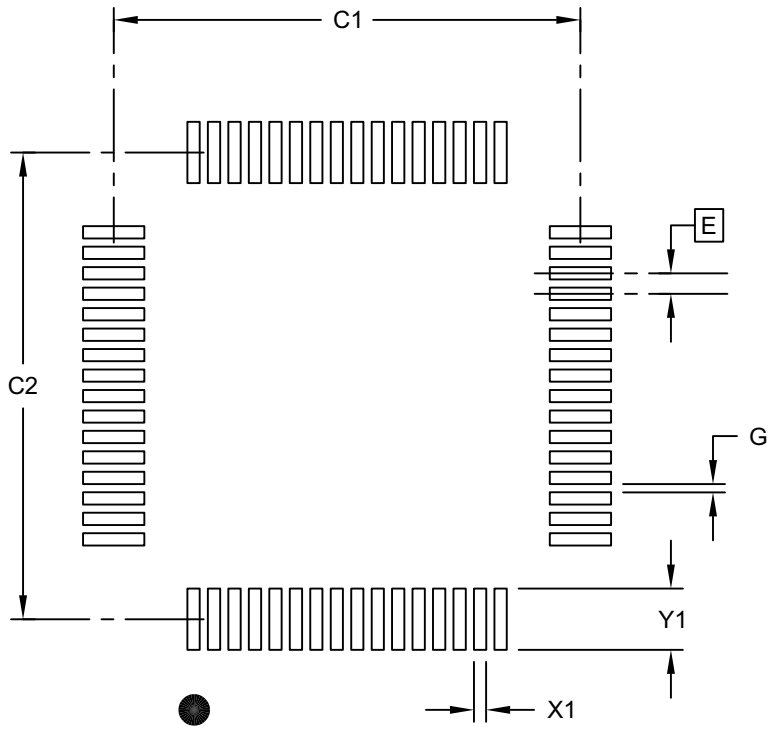
TABLE 33-25: A/D MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 2.2	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 1.7	—	AVDD	V	
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 1.7	V	
AD07	VREF	Absolute Reference Voltage	AVSS – 0.3	—	AVDD + 0.3	V	
Analog Inputs							
AD10	VINH-VINL	Full-Scale Input Span	VREFL	—	VREFH	V	**(Note 1)**
AD11	VIN	Absolute Input Voltage	AVSS – 0.3	—	AVDD + 0.3	V	
AD12	VINL	Absolute VINL Input Voltage	AVSS – 0.3	—	AVDD/3	V	
AD13		Leakage Current	—	±1.0	±610	nA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V, Source Impedance = 2.5 kΩ
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	2.5K	Ω	10-bit
A/D Accuracy							
AD20B	Nr	Resolution	—	12	—	bits	
AD21B	INL	Integral Nonlinearity	—	±1	< ±2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD22B	DNL	Differential Nonlinearity	—	—	< ±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD23B	GERR	Gain Error	—	±1	±4	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD24B	EOFF	Offset Error	—	±1	±2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD25B		Monotonicity(1)	—	—	—	—	Guaranteed

Note 1: Measurements are taken with the external VREF+ and VREF- used as the A/D voltage reference.

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X28)	X1			0.30
Contact Pad Length (X28)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2085B Sheet 1 of 1

NOTES: